

Breakdown of component	Material Name	Substance Name	CAS No.	Substance Mass		Material Mass (wt%)
				(mg)	(wt%)	
Lid	Kovar Lid	Nickel (Ni)	7440-02-0	0.63228	30.0	4.4344
		Cobalt (Co)	7440-48-4	0.36883	17.5	2.5867
		Iron (Fe)	7439-89-6	1.10649	52.5	7.7602
Blank	Crystal Blank	Silicon dioxide (SiO2)	14808-60-7	0.57455	99.97	4.0295
		Aluminum oxide (Al2O3)	1344-28-1	0.00008	0.014	0.0006
		Ferric oxide (Fe2O3)	1309-37-1	0.00009	0.016	0.0006
Base	Ceramic	Aluminum oxide (Al2O3)	1344-28-1	5.8105	90.0	40.7510
		Silicon oxide (SiO2)	7631-86-9	0.3874	6.0	2.7167
		Chromium oxide (Cr2O3)	1308-38-9	0.1291	2.0	0.9056
		Molybdenum (Mo)	7439-98-7	0.1291	2.0	0.9056
	Metallizing	Tungsten (W)	7440-33-7	1.7522	100.0	12.2887
	Seal ring	Iron (Fe)	7439-89-6	1.0768	53.0	7.5522
		Nickel (Ni)	7440-02-0	0.5892	29.0	4.1323
		Cobalt (Co)	7440-48-4	0.3657	18.0	2.5649
	Solder	Silver (Ag)	7440-22-4	0.3847	71.0	2.6979
		Copper (Cu)	7440-50-8	0.1571	29.0	1.1020
	Ni Plate	Nickel (Ni)	7440-02-0	0.0271	100.0	0.1900
	Au Plate	Gold (Au)	7440-57-5	0.0271	100.0	0.1900
IC	Wafer	Silicon(Si)	7440-21-3	0.2622	100.0	1.8392
	D/B adhesive	Silanamine, 1,1,1-trimethyl-N-(trimethylsilyl)-, hydrolysis products with silica	68909-20-6	0.1851	40.0	1.2984
		Fatty acids, C18-unsatd., dimers, hydrogenated, di-Me esters, hydrogenated, bis(2,5-dihydro-2,5-dioxo-1H- pyrrole	NA	0.1388	30.0	0.9738
		Filler	Trade Secret	0.0694	15.0	0.4869
		Acrylate monomer	Trade Secret	0.0231	5.0	0.1623
		Epoxy resin	Trade Secret	0.0231	5.0	0.1623
	Additive	Trade Secret	0.0231	5.0	0.1623	
Au wire	Gold(Au)	7440-57-5	0.0091	100.0	0.0635	
Adhesive	DOTITE	Silver (Ag)	7440-22-4	0.000122	76.3	0.0009
		Silicone Resin	NA	0.0000234	14.6	0.00016
		n-Dodecane (C12H26)	112-40-3	0.0000133	8.3	0.00009
		Alkoxysilane (C11H22O4Si)	3388-04-3	0.0000013	0.8	0.00001
Electrode	Ag	Silver (Ag)	7440-22-4	0.00591	100.0	0.0415
TOTAL				14.25851		100.0000